



Client is in the semiconductor industry by developing strategic competencies, innovative technologies and intellectual property; enabling enterprises to be technologically competitive; and cultivating a technology talent pool to inject new knowledge to the industry.

MICROSYSTEMS, MODULES & COMPONENTS LABORATORY

Senior Research Engineer – Wafer Level Packaging

This position deals with the design and development of embedded wafer level packaging, with emphasis on wafer level molding, wafer level RDL processes, flip-chip assembly and wafer thinning.

Responsibilities:

The key responsibilities will include wafer level package design, process/material selection, ultra-wafer thinning and wafer handling, as well as, process integration for embedded wafer level packaging and die embedding.

Requirements:

- PhD degree in Mechanical Engineering/Material Science with at least 3 years of related industrial/research experience
- Knowledge on packaging material selection and package reliability test methods
- Experience in project scoping and execution of the projects independently
- Excellent communication skills and teamwork with strong self-motivation

Interested candidates are invited to submit your latest updated resume stating your availability of employment, current, achievements and expected salary to Adrian Collin Png at: adrian@collincrawford.com